

Title (en)  
ADHESIVE COMPOSITIONS THAT ARE REMOVABLE AFTER THERMOSETTING

Title (de)  
NACH HITZEHÄRTUNG ABNEHMBARE KLEBSTOFFZUSAMMENSETZUNGEN

Title (fr)  
COMPOSITIONS ADHESIVES ENLEVABLES APRES THERMODURCISSEMENT

Publication  
**EP 0980409 A1 20000223 (EN)**

Application  
**EP 97925450 A 19970505**

Priority  
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Abstract (en)  
[origin: WO9850480A1] Thermosettable adhesive compositions that include a polyepoxide resin, a curing agent, and a plurality of microspheres. The microspheres, polyepoxide resin, and curing agent and the relative amounts thereof, are selected such that upon cure the composition is capable of forming a semi-structural bond to a substrate and is cleanly thermally removable from the substrate.

IPC 1-7  
**C09J 163/00**; **C09J 133/06**

IPC 8 full level  
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CPC (source: EP US)  
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**C09J 2463/00** (2013.01 - EP)

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See references of WO 9850480A1

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